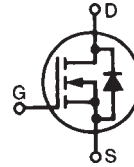


PolarHV™ HiPerFET IXFH 140N10P Power MOSFETs IXFT 140N10P

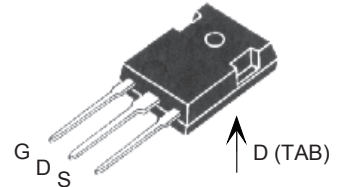
N-Channel Enhancement Mode
Fast Intrinsic Diode
Avalanche Rated



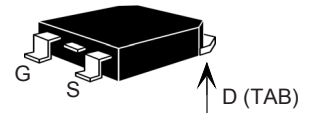
$$\begin{aligned} V_{DSS} &= 100 \text{ V} \\ I_{D25} &= 140 \text{ A} \\ R_{DS(on)} &\leq 11 \text{ m}\Omega \\ t_{rr} &\leq 150 \text{ ns} \end{aligned}$$

| Symbol | Test Conditions | Maximum Ratings | |
|--------------|---|-----------------|------------------|
| V_{DSS} | $T_J = 25^\circ\text{C}$ to 175°C | 100 | V |
| V_{DGR} | $T_J = 25^\circ\text{C}$ to 175°C ; $R_{GS} = 1 \text{ M}\Omega$ | 100 | V |
| V_{GS} | Continuous | ± 20 | V |
| V_{GSM} | Transient | ± 30 | V |
| I_{D25} | $T_C = 25^\circ\text{C}$ | 140 | A |
| $I_{D(RMS)}$ | External lead current limit | 75 | A |
| I_{DM} | $T_C = 25^\circ\text{C}$, pulse width limited by T_{JM} | 300 | A |
| I_{AR} | $T_C = 25^\circ\text{C}$ | 60 | A |
| E_{AR} | $T_C = 25^\circ\text{C}$ | 80 | mJ |
| E_{AS} | $T_C = 25^\circ\text{C}$ | 2.5 | J |
| dv/dt | $I_S \leq I_{DM}$, $di/dt \leq 100 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 4 \Omega$ | 10 | V/ns |
| P_D | $T_C = 25^\circ\text{C}$ | 600 | W |
| T_J | | -55 ... +175 | $^\circ\text{C}$ |
| T_{JM} | | 175 | $^\circ\text{C}$ |
| T_{stg} | | -55 ... +150 | $^\circ\text{C}$ |
| T_L | 1.6 mm (0.062 in.) from case for 10 s | 300 | $^\circ\text{C}$ |
| T_{SOLD} | Plastic body for 10s | 260 | $^\circ\text{C}$ |
| M_d | Mounting torque (TO-247) | 1.13/10 | Nm/lb.in. |
| Weight | TO-247 | 6.0 | g |
| | TO-268 | 5.0 | g |

TO-247 (IXFH)



TO-268 (IXFT)



G = Gate D = Drain
S = Source TAB = Drain

Features

- † International standard packages
- † Unclamped Inductive Switching (UIS) rated
- † Low package inductance
- easy to drive and to protect

Advantages

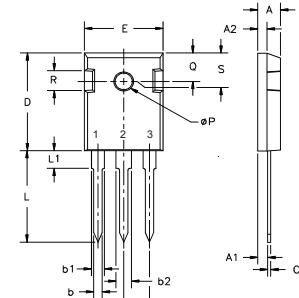
- † Easy to mount
- † Space savings
- † High power density

| Symbol | Test Conditions | Characteristic Values | | |
|--------------|--|-----------------------|------|-----------------------------------|
| | | Min. | Typ. | Max. |
| BV_{DSS} | $V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$ | 100 | | V |
| $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 4.0 \text{ mA}$ | 3.0 | | 5.0 V |
| I_{GSS} | $V_{GS} = \pm 20 \text{ V}_{DC}$, $V_{DS} = 0$ | | | $\pm 100 \text{ nA}$ |
| I_{DSS} | $V_{DS} = V_{DSS}$ $V_{GS} = 0 \text{ V}$ $T_J = 175^\circ\text{C}$ | | | 25 μA |
| | | | | 500 μA |
| $R_{DS(on)}$ | $V_{GS} = 10 \text{ V}$, $I_D = 0.5 I_{D25}$ $V_{GS} = 15 \text{ V}$, $I_D = 300 \text{ A}$ Note 1 | 9 | | 11 $\text{m}\Omega$ m Ω |

| Symbol | Test Conditions | Characteristic Values | | |
|---------------------------|---|--|-------|-----------|
| | | (T _J = 25° C, unless otherwise specified) | | |
| | | Min. | Typ. | Max. |
| g_{fs} | V _{DS} = 10 V; I _D = 0.5 I _{D25} , Note 1 | 45 | 65 | S |
| C_{iss} | V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz | | 4700 | pF |
| C_{oss} | | 1850 | pF | |
| C_{rss} | | 600 | pF | |
| t_{d(on)} | V _{GS} = 10 V, V _{DS} = 0.5 V _{DSS} , I _D = 60 A R _G = 4 Ω (External) | | 35 | ns |
| t_r | | 50 | ns | |
| t_{d(off)} | | 85 | ns | |
| t_f | | 26 | ns | |
| Q_{g(on)} | V _{GS} = 10 V, V _{DS} = 0.5 V _{DSS} , I _D = 0.5 I _{D25} | | 155 | nC |
| Q_{gs} | | 33 | nC | |
| Q_{gd} | | 85 | nC | |
| R_{thJC} | (TO-247) | | | 0.25° C/W |
| R_{thCS} | | 0.21 | ° C/W | |

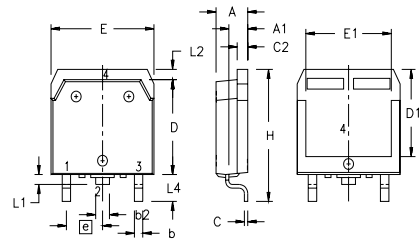
| Symbol | Test Conditions | Characteristic Values | | |
|-----------------------|--|--|------|--------|
| | | (T _J = 25° C, unless otherwise specified) | | |
| | | Min. | Typ. | Max. |
| I_s | V _{GS} = 0 V | | | 140 A |
| I_{SM} | Repetitive | | | 300 A |
| V_{SD} | I _F = I _S , V _{GS} = 0 V, Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 % | | | 1.5 V |
| t_{rr} | I _F = 25 A, -di/dt = 100 A/μs V _R = 50 V, V _{GS} = 0 V | | 150 | 200 ns |
| Q_{RM} | | 0.8 | μC | |
| I_{RM} | | 6 | A | |

Note 1: Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %

TO-247 AD Outline


Terminals: 1 - Gate
2 - Drain
3 - Source
Tab - Drain

| Dim. | Millimeter | | Inches | |
|----------------|------------|-------|--------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.7 | 5.3 | .185 | .209 |
| A ₁ | 2.2 | 2.54 | .087 | .102 |
| A ₂ | 2.2 | 2.6 | .059 | .098 |
| b | 1.0 | 1.4 | .040 | .055 |
| b ₁ | 1.65 | 2.13 | .065 | .084 |
| b ₂ | 2.87 | 3.12 | .113 | .123 |
| C | .4 | .8 | .016 | .031 |
| D | 20.80 | 21.46 | .819 | .845 |
| E | 15.75 | 16.26 | .610 | .640 |
| e | 5.20 | 5.72 | 0.205 | 0.225 |
| L | 19.81 | 20.32 | .780 | .800 |
| L ₁ | | 4.50 | | .177 |
| ∅P | 3.55 | 3.65 | .140 | .144 |
| Q | 5.89 | 6.40 | 0.232 | 0.252 |
| R | 4.32 | 5.49 | .170 | .216 |
| S | 6.15 | BSC | 242 | BSC |

TO-268 Outline


| SYM | INCHES | | MILLIMETERS | |
|-----|--------|----------|-------------|----------|
| | MIN | MAX | MIN | MAX |
| A | .193 | .201 | 4.90 | 5.10 |
| A1 | .106 | .114 | 2.70 | 2.90 |
| A2 | .001 | .010 | 0.02 | 0.25 |
| b | .045 | .057 | 1.15 | 1.45 |
| b2 | .075 | .083 | 1.90 | 2.10 |
| C | .016 | .026 | 0.40 | 0.65 |
| C2 | .057 | .063 | 1.45 | 1.60 |
| D | .543 | .551 | 13.80 | 14.00 |
| D1 | .488 | .500 | 12.40 | 12.70 |
| E | .624 | .632 | 15.85 | 16.05 |
| E1 | .524 | .535 | 13.30 | 13.60 |
| e | | .215 BSC | | 5.45 BSC |
| H | .736 | .752 | 18.70 | 19.10 |
| L | .094 | .106 | 2.40 | 2.70 |
| L1 | .047 | .055 | 1.20 | 1.40 |
| L2 | .039 | .045 | 1.00 | 1.15 |
| L3 | | .010 BSC | | 0.25 BSC |
| L4 | .150 | .161 | 3.80 | 4.10 |

IXYS reserves the right to change limits, test conditions, and dimensions.

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4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2

Fig. 1. Output Characteristics
@ 25°C

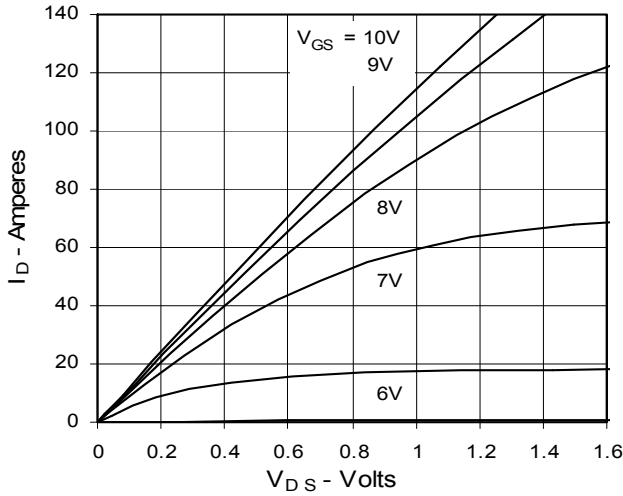


Fig. 2. Extended Output Characteristics
@ 25°C

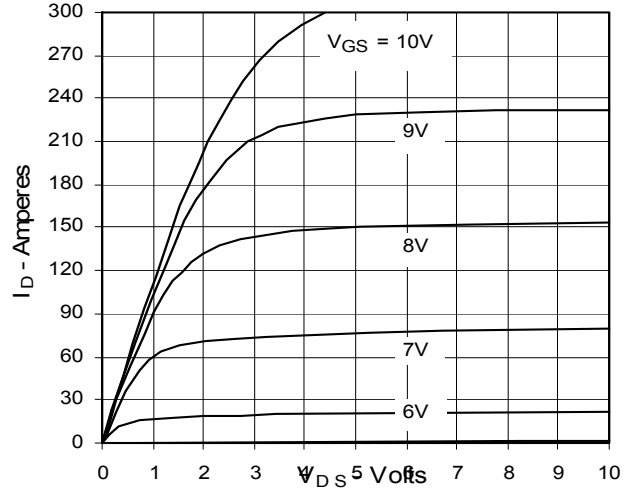


Fig. 3. Output Characteristics
@ 150°C

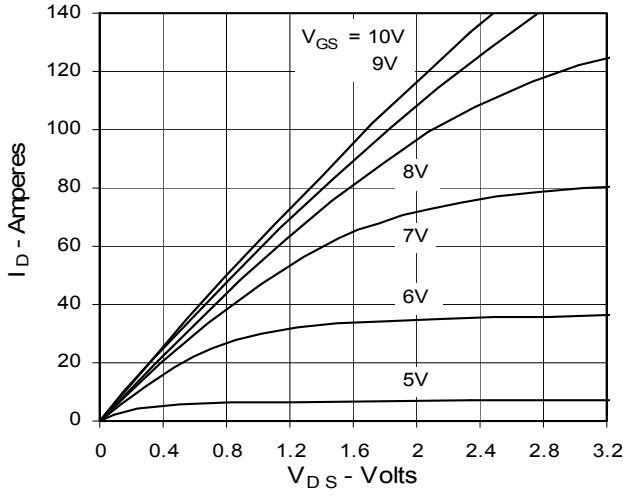


Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Junction Temperature

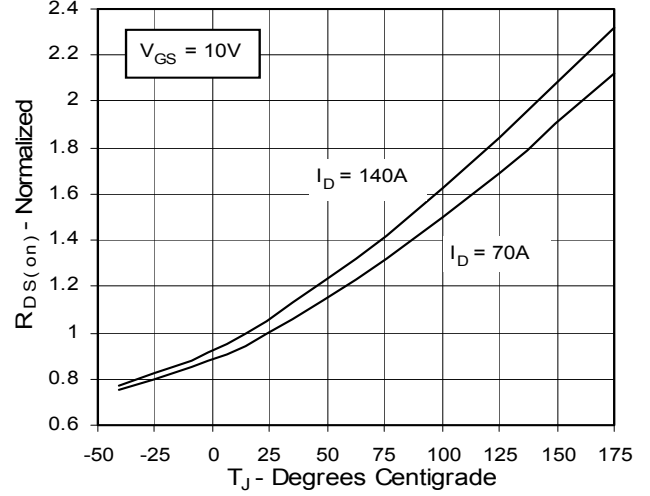


Fig. 5. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Drain Current

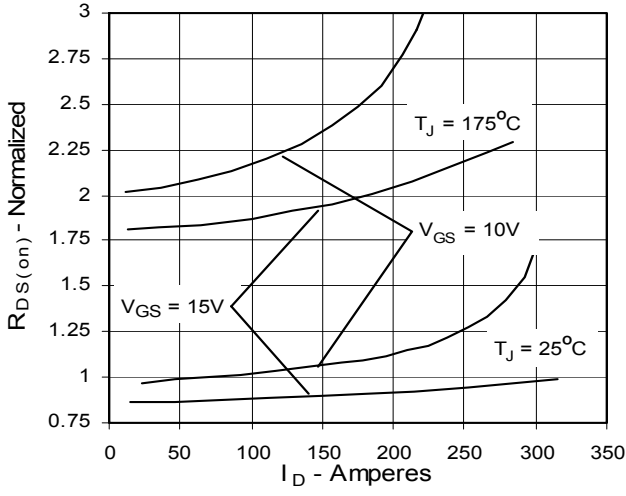


Fig. 6. Drain Current vs. Case Temperature

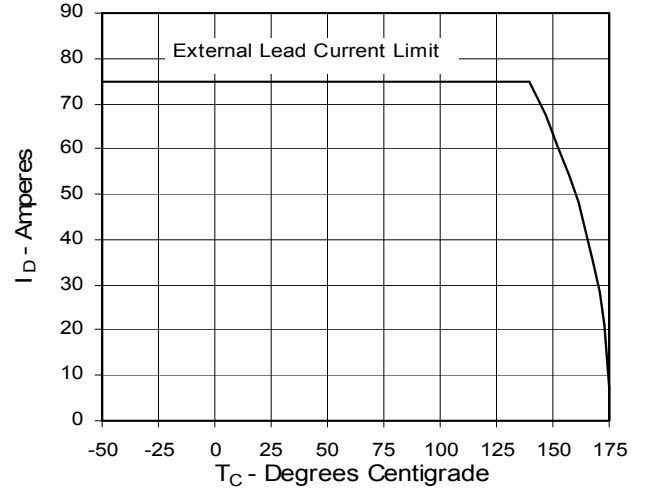


Fig. 7. Input Admittance

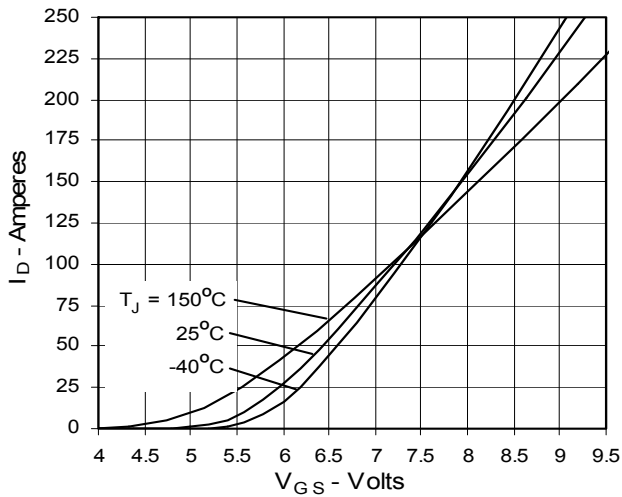


Fig. 8. Transconductance

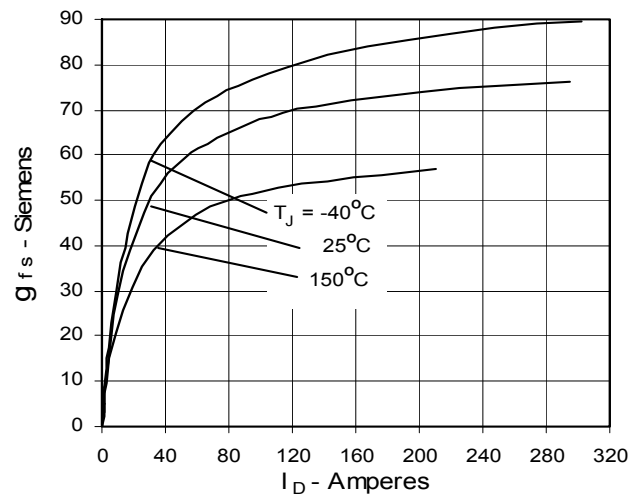


Fig. 9. Source Current vs. Source-To-Drain Voltage

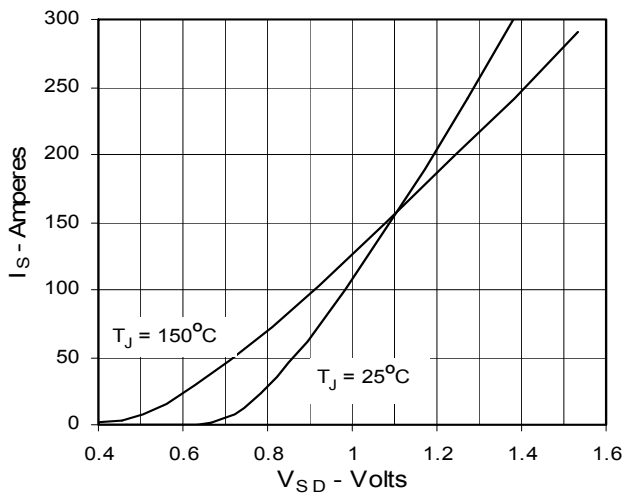


Fig. 10. Gate Charge

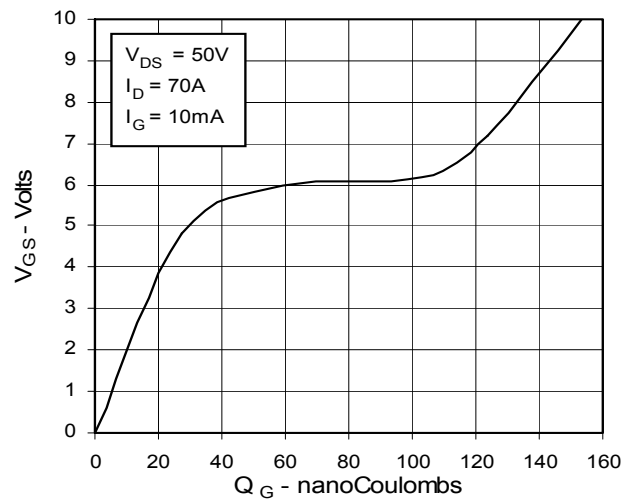


Fig. 11. Capacitance

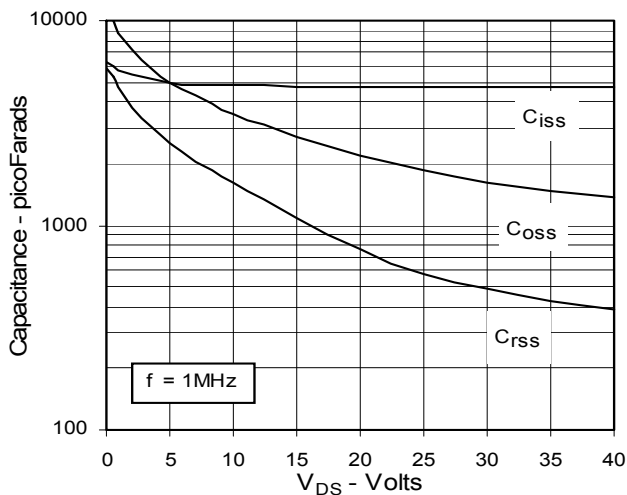


Fig. 12. Forward-Bias Safe Operating Area

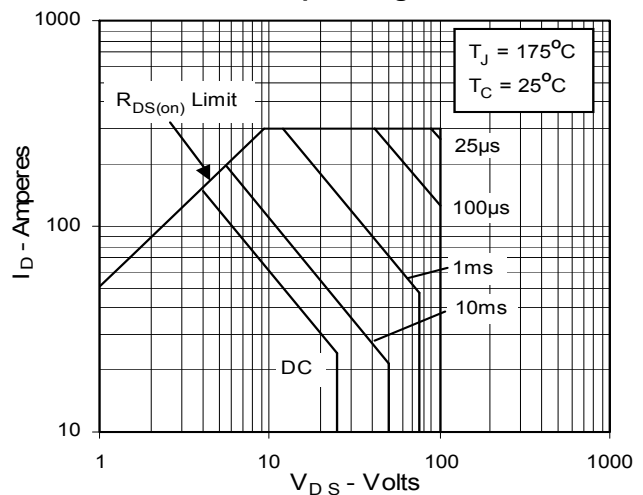
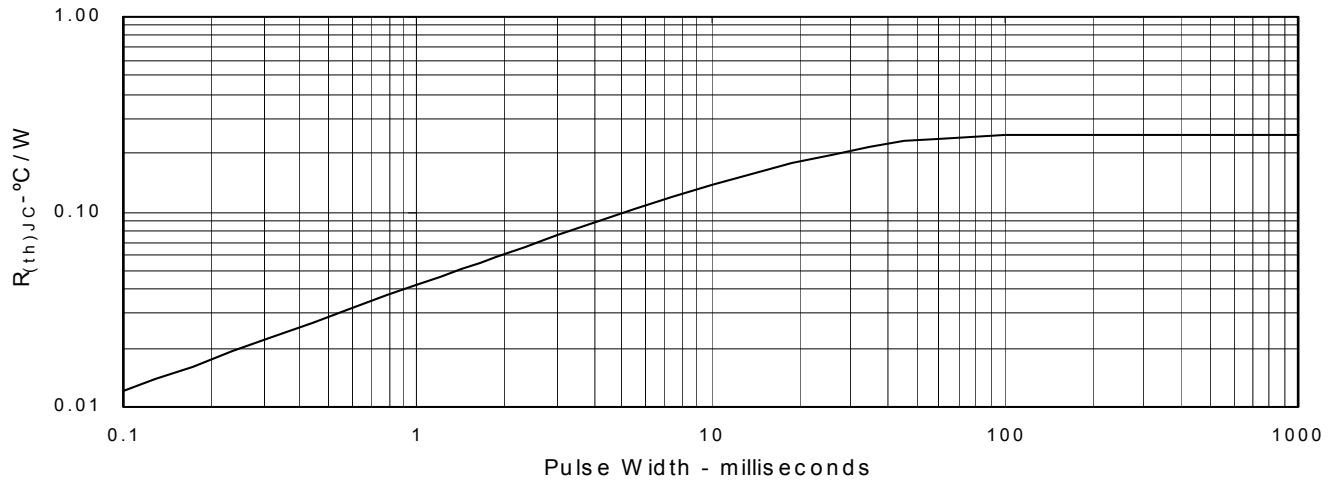


Fig. 13. Maximum Transient Thermal Resistance





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